2SD2225

Silicon NPN epitaxial planer type

For low-frequency amplification Complementary to 2SB1473

Features

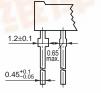
- High collector to emitter voltage V_{CEO} of 120V.
- Optimum for low-frequency driver amplification.
- Allowing supply with the radial taping.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	120	V
Collector to emitter voltage	V_{CEO}	120	V
Emitter to base voltage	V_{EBO}	5	V
Peak collector current	I_{CP}	1	A
Collector current	I_{C}	0.5	A
Collector power dissipation	${P_C}^*$	1	W
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	−55 ~ +150	°C

^{*} Printed circuit board: Copper foil area of 1cm² or more, and the board thickness of 1.7mm for the collector portion

Unit: mm Note: In addition to the 1:Emitter lead type shown in 2:Collector the upper figure, the 3:Base MT2 Type Package type as shown in the lower figure is also available.



(HW type)

Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions r		typ	max	Unit
Collector to emitter voltage	V _{CEO}	$I_C = 0.1 \text{mA}, I_B = 0$	120			V
Emitter to base voltage	V _{EBO}	$I_E = 10\mu A, I_C = 0$	5			V
Forward current transfer ratio	h _{FE1} *1	$V_{CE} = 10V, I_{C} = 150 \text{mA}^{*2}$	90		330	
	h _{FE2}	$V_{CE} = 5V, I_{C} = 500 \text{mA}^{*2}$	50			
	h _{FE3}	$V_{CE} = 5V, I_C = 100 \text{mA}^{*2}$	100			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 300 \text{mA}, I_B = 30 \text{mA}^{*2}$		0.15	1	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = 300 \text{mA}, I_B = 30 \text{mA}^{*2}$		0.9	1.2	V
Transition frequency	f_{T}	$V_{CB} = 10V, I_E = -50mA, f = 200MHz^{*2}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10V, I_{E} = 0, f = 1MHz$		11.5	20	pF

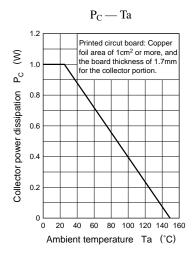
^{*2} Pulse measurement

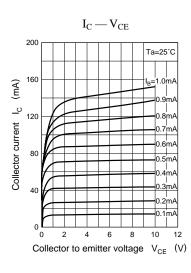
h_{FE1} Rank classification

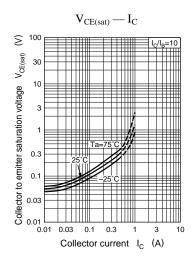
121			
找Rank PE	F Q	R	S
pret	90 ~ 155	130 ~ 220	185 ~ 330
1000			

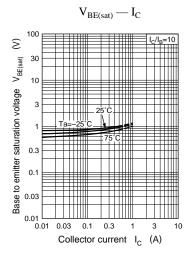
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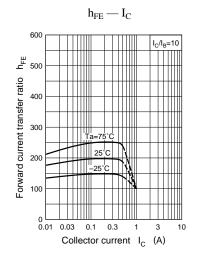
Transistor 2SD2225

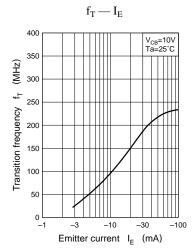


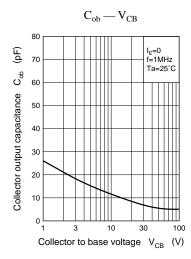












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